

DHI-DDR-C300

Memory Module





- \cdot Uses featured DRAM chip to provide great performance and high-speed data transmission.
- · Curved gold finger to ensure stable installation and signal transmission.
- · Reliable quality and lifetime warranty.
- · Highly compatible; supports mainstream platforms such as Intel and AMD; plug-and-play.

System Overview

The C300 series memory modules are DDR4 DRAM products with SODIMM and UDIMM models. With operating frequency of 2666 MHZ, they not only provide faster data exchange speed, but also greatly improve the overall performance of the system.

Functions

Featured DRAM Chip and Great Performance

Uses high-quality DRAM chip to provide great performance and long service life.

Meet Various Needs

Meets the needs of consumers for PC memory replacement and device upgrade to provide fast experience.

Compatible with Various Products

Compatible with Intel and AMD platforms; passes tests with various motherboards of well-known brands; highly compatible and stable.

Scene

The C300 series is designed to meet the needs of consumers for PC memory replacement and device upgrade. The operating frequency is as high as 2666 MHz to support multi-thread and multi-task operation of the system. They can be widely used in laptops, desktops, all-in-one computers, and more.

Technical Specification

Technical

Product Model	DHI-DDR- C300S4G26	DHI-DDR- C300S8G26	DHI-DDR- C300S16G26	DHI-DDR- C300S32G26
Capacity	4 GB	8 GB	16 GB	32 GB
Туре	SODIMM			
Applicable Model	DDR4 laptop			
Voltage	1.2 V			
CAS Latency	CL19			
Operating Frequency	2666 MHz			
Number of Pins	260			
Operating Temperature	0 °C to +70 °C	(+32 °F to 158 °	F)	
Storage Temperature	20 °C to +85 °	C (-4 °F to +185	°F)	
Operating Humidity	25%-85% (no	n-condensing)		
Warranty	Lifetime			
Product Dimensions	69.6 mm × 30	mm × 3.58 mm	(2.74" × 1.18" ×	(0.14")(1)
Packaging Dimensions	165 mm × 51	mm × 16.5 mm	(6.50" × 2.01" ×	0.65")
Net Weight	8.5 g (0.02 lb)			
Gross Weight	36 g (0.08 lb)			



	Note: ①The thickness is calculated at the thickest point. 1. For different batches of products, memory chips of different brands and models will be used. All chips have been strictly tested to ensure quality. Chip brand and testing results of third-party softwares cannot be the basis for
Reference Information	whether the product is genuine. 2. For products with the same capacity, there are 8 chips and 16 chips, which will be shipped randomly according to the inventory. 3. For memory modules of the same generation, the operating frequency is backward compatible. For example, the frequency of DDR4 includes 2400, 2666, 3000 and more. The memory module with the frequency of 3000 can be used in motherboards supporting 2666 or 2400 with lower
	frequency.

Technical Specification

Technical

Product Model	DHI-DDR- C300S4G32	DHI-DDR- C300S8G32	DHI-DDR- C300S16G32	DHI-DDR- C300S32G32
Capacity	4 GB	8 GB	16 GB	32 GB
Туре	SODIMM			
Applicable Model	DDR4 laptop			
Voltage	1.2 V			
CAS Latency	CL22			
Operating Frequency	3200 MHz			
Number of Pins	260			
Operating Temperature	0 °C to +70 °C	(+32 °F to 158 °	F)	
Storage Temperature	20 °C to +85 °	C (-4 °F to +185	°F)	
Operating Humidity	25%-85% (no	n-condensing)		
Warranty	Lifetime			
Product Dimensions	69.6 mm × 30	mm × 3.58 mm	(2.74" × 1.18" >	(0.14")(1)
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Technical Specification

Technical

Product Model DHI-DDR-C300U8G26 C300U8G26 C300U1GG26 Capacity 4 GB 8 GB 16 GB 32 GB Type UDIMM Applicable Model DDR4 desktop Voltage 1.2 V CAS Latency CL19 Operating Frequency 2666 MHz Number of Pins 288 Operating Temperature 20 °C to +85 °C (-4 °F to +185 °F) Storage Temperature 25%-85% (non-condensing) Warranty Lifetime Product Dimensions 69.6 mm × 30 mm × 3.58 mm (2.74" × 1.18" × 0.14") ① Packaging Dimensions 165 mm × 51 mm × 16.5 mm (6.50" × 2.01" × 0.65") Net Weight 44 g (0.10 lb) Note: ① The thickness is calculated at the thickest point. 1. For different batches of products, memory chips of different brands and models will be used. All chips have been strictly tested to ensure quality. Chip brand and testing results of third-party softwares cannot be the basis for whether the product is genuine. 2. For products with the same capacity, there are 8 chips and 16 chips, which will be shipped randomly according to the inventory. 3. For memory modules of the same generation, the operating frequency of DDR4 includes 2400, 2666, 3000 and more. The memory module with the frequency of 3000 can be used in motherboards supporting 2666 or 2400 with lower frequency.	recnnicai				
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	Reference Information	1. For different different bran- been strictly to results of third whether the particular 2. For product 16 chips, which inventory. 3. For memory operating free the frequency. The memory rused in mother	t batches of pro ds and models v ested to ensure d-party software product is genuin as with the same th will be shippe y modules of the juency is backwa of DDR4 include module with the	ducts, memory vill be used. All of quality. Chip brates cannot be the see. If capacity, there depends a comparity according to the capacity of	chips of chips have and and testing basis for are 8 chips and ording to the on, the For example, 1000 and more.

Technical Specification

Technical

Product Model	DHI-DDR- C300U4G32	DHI-DDR- C300U8G32	DHI-DDR- C300U16G32	DHI-DDR- C300U32G32
Capacity	4 GB	8 GB	16 GB	32 GB
Туре	UDIMM			
Applicable Model	DDR4 desktop			
Voltage	1.2 V			
CAS Latency	CL22			
Operating Frequency	3200 MHz			
Number of Pins	288			
Operating Temperature	0 °C to +70 °C	(+32 °F to 158 °	F)	

Storage Temperature	20 °C to +85 °C (-4 °F to +185 °F)
Operating Humidity	25%–85% (non-condensing)
Warranty	Lifetime
Product Dimensions	69.6 mm × 30 mm × 3.58 mm (2.74" × 1.18" × 0.14")①
Packaging Dimensions	165 mm × 51 mm × 16.5 mm (6.50" × 2.01" × 0.65")
Net Weight	16 g (0.04 lb)
Gross Weight	44 g (0.10 lb)
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	DHI-DDR-C300U8G32	C300 Series DDR4 3200 8 GB Memory Module for Desktops
Portable Solid State Drive	DHI-DDR- C300U16G32	C300 Series DDR4 3200 16 GB Memory Module for Desktops
	DHI-DDR- C300U32G32	C300 Series DDR4 3200 32 GB Memory Module for Desktops
Dimensions	(mm[inch])	

99.6 (2.74)	1.45 (0.06) 3.85 (0.15)	
January e etchings		

Ordering Information		
Туре	Model	Description
	DHI-DDR-C300S4G26	C300 Series DDR4 2666 4 GB Memory Module for Laptops
	DHI-DDR-C300S8G26	C300 Series DDR4 2666 8 GB Memory Module for Laptops
	DHI-DDR-C300S16G26	C300 Series DDR4 2666 16 GB Memory Module for Laptops
	DHI-DDR-C300S32G26	C300 Series DDR4 2666 32 GB Memory Module for Laptops
	DHI-DDR-C300S4G32	C300 Series DDR4 3200 4 GB Memory Module for Laptops
	DHI-DDR-C300S8G32	C300 Series DDR4 3200 8 GB Memory Module for Laptops
Portable Solid State Drive	DHI-DDR-C300S16G32	C300 Series DDR4 3200 16 GB Memory Module for Laptops
	DHI-DDR-C300S32G32	C300 Series DDR4 3200 32 GB Memory Module for Laptops
	DHI-DDR-C300U8G26	C300 Series DDR4 2666 4 GB Memory Module for Desktops

C300 Series DDR4 2666 8 GB Memory

C300 Series DDR4 2666 16 GB Memory

C300 Series DDR4 2666 32 GB Memory

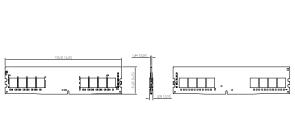
C300 Series DDR4 3200 4 GB Memory

Module for Desktops

Module for Desktops

Module for Desktops

Module for Desktops



Rev 001.000



DHI-DDR-C300U8G26

DHI-DDR-C300U8G32

DHI-DDR-

DHI-DDR-

C300U16G26

C300U32G26